

- NOTES:
- MATERIAL:
HOUSING - POLYAMIDE (PA) GLASS FILLED, UL 94V-0, COLOR - BLACK
LATCH - POLYAMIDE (PA) GLASS FILLED, UL 94V-0, COLOR - BLACK
TERMINAL - COPPER ALLOY
 - FINISHES: TERMINAL PLATING SEE TABLE ON SHEET 5
 - PRODUCT SPECIFICATION: PS-78315-001
 - PACKAGING SPECIFICATION: PRODUCT SHALL BE PACKED IN TRAYS
 - CARD SLOT ACCEPTS 1.27 +/- 0.10MM MODULE THICKNESS (MEASURED FROM PC PADS)

- 6 MOLEX LOGO, DATE & PART NUMBERS INDICATED ON HOUSING
- 7 MODULE SEATING PLANE FROM TOP OF PCB
- 8 KEEP OUT ZONE RESERVED FOR LATCH

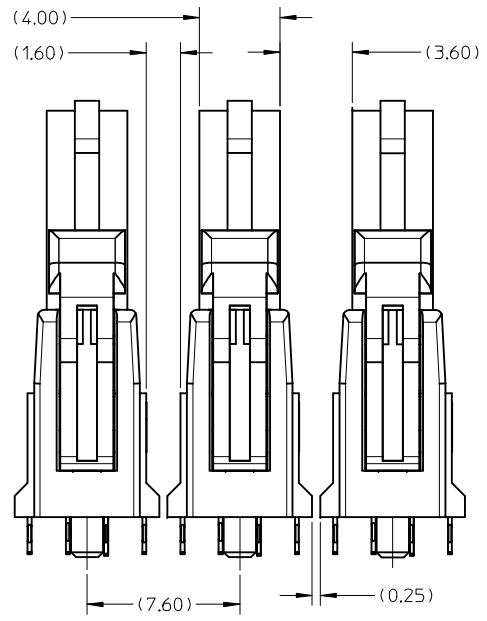
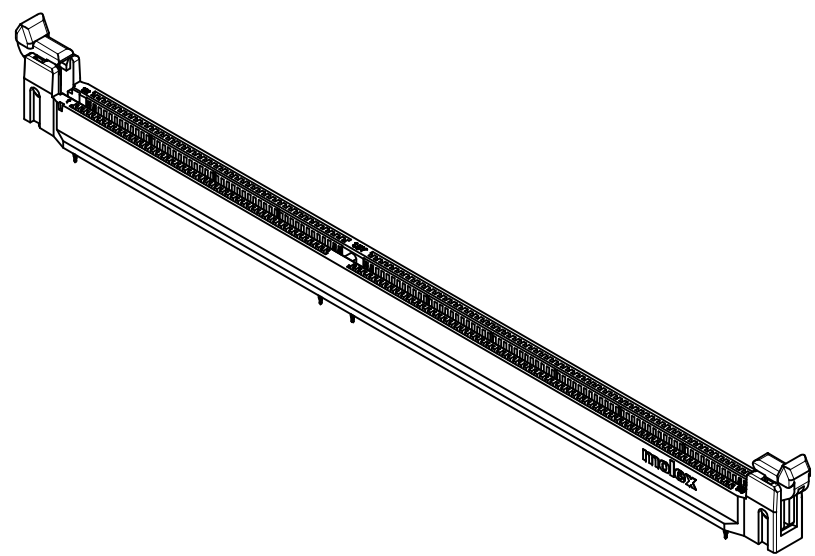
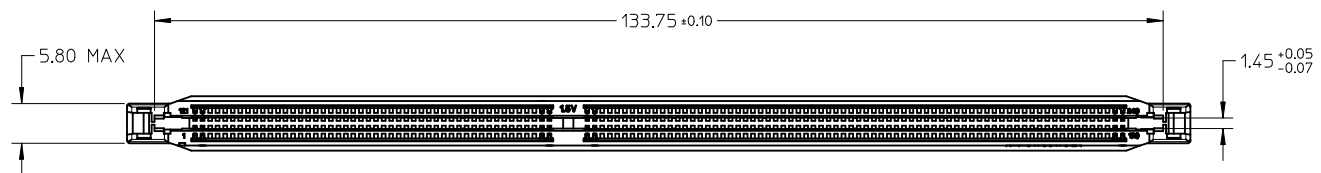
| | | |
|--|---------------------------------------|----|
| OBS. 78315-0201 EC NO: S2013-0172 DRW:NCCTEH 2012/09/27 CHKD:CGTAN 2012/10/08 APPR:SHLENI 2012/10/12 | REV | A2 |
| | DESCRIPTION | |
| | QUALITY SYMBOLS | |
| | GENERAL TOLERANCES (UNLESS SPECIFIED) | |

| QUALITY SYMBOLS | GENERAL TOLERANCES (UNLESS SPECIFIED) | |
|-----------------|--|-------|
| | mm | INCH |
| $F_A=0$ | 4 PLACES ± --- | ± --- |
| $F_G=0$ | 3 PLACES ± --- | ± --- |
| $F_B=0$ | 2 PLACES ± 0.20 | ± --- |
| | 1 PLACE ± --- | ± --- |
| | 0 PLACE ± --- | ± --- |
| | ANGULAR ± 1 ° | |
| | DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS | |

| DIMENSION STYLE | |
|-----------------|------------|
| MM ONLY | |
| DRAWN BY | DATE |
| CMTEO | 2008/07/17 |
| CHECKED BY | DATE |
| CCTEH | 2008/07/30 |
| APPROVED BY | DATE |
| SHLENI | 2010/12/15 |
| MATERIAL NO. | |
| SEE TABLE | |
| SIZE | A3 |

| | | | | |
|---|-----|--------------|--------|------------------------|
| SCALE | NTS | DESIGN UNITS | METRIC | THIRD ANGLE PROJECTION |
| TITLE | | | | |
| DDR3 DIMM (LSP, VLP) 100MM PITCH, 240 CKTS VERTICAL P/F, LOWLLCR | | | | |
| DOCUMENT NO. | | | | SHEET NO. |
| SD-78315-001 | | | | 1 OF 6 |
| THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION | | | | |

10 9 8 7 6 5 4 3 2 1



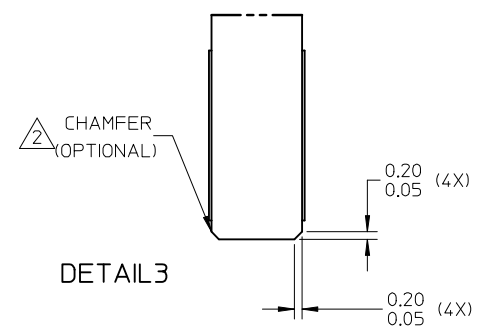
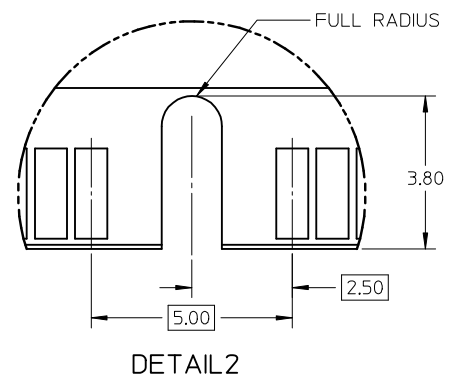
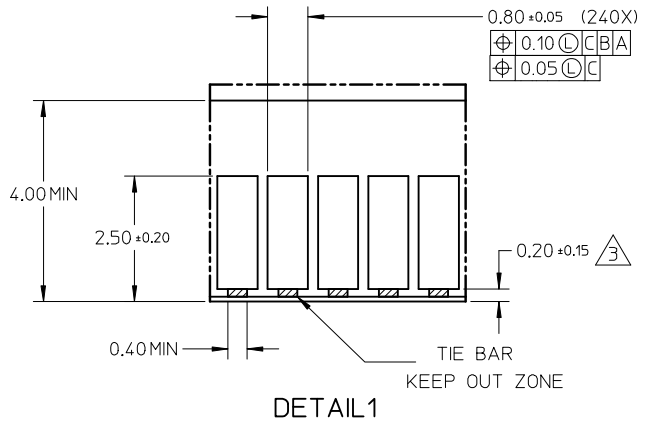
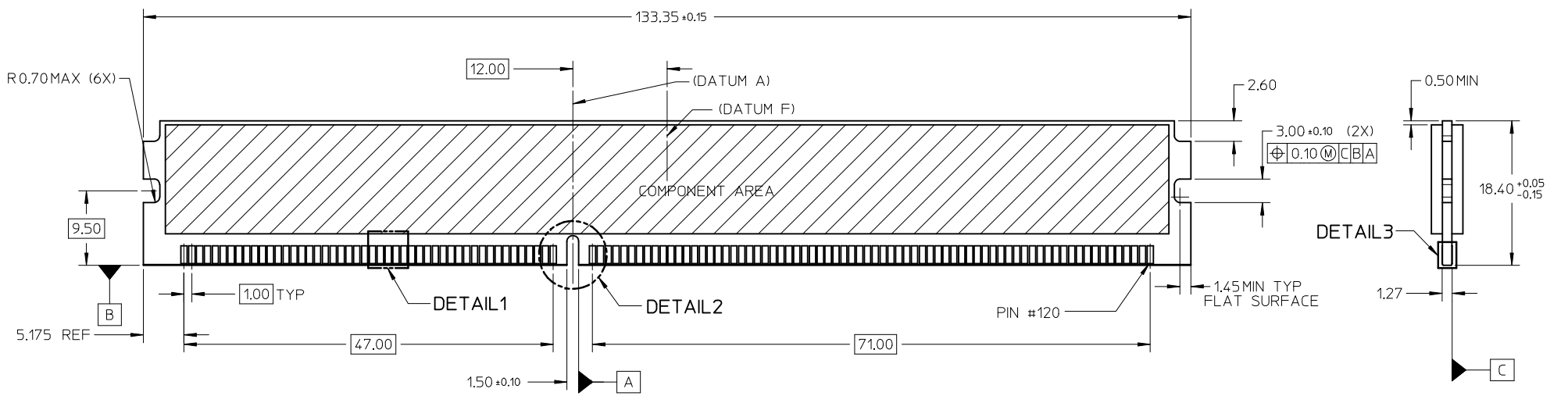
MINIMUM ROW TO ROW SPACING RECOMMENDATION
(USING 4.00MM MODULE CARD)

| | | | | | | | | | | |
|---|-----------|---------------|--|---------------------------------------|----------------------|--|--------------------|--|------------------------|------------------------|
| OBS. 78315-0201 EC NO: S2013-0172 DRWN: CCTEH 2012/09/27 CHKD: CGTAN 2012/10/08 APPR: SHLENI 2012/10/12 | REV A2 | DESCRIPTION | QUALITY SYMBOLS F _A =0 F _G =0 F _P =0 | GENERAL TOLERANCES (UNLESS SPECIFIED) | | DIMENSION STYLE MM ONLY | | SCALE NTS | DESIGN UNITS METRIC | THIRD ANGLE PROJECTION |
| | | | | mm | INCH | DRAWN BY CMTEO | DATE 2008/07/17 | TITLE DDR3 DIMM (LSP, VLP) 1.00MM PITCH, 240 CKTS VERTICAL P/F, LOWLLCR | | |
| | | | | 4 PLACES ± --- ± --- | 3 PLACES ± --- ± --- | CHECKED BY CCTEH | DATE 2008/07/30 | molex | | |
| | | | | 2 PLACES ± 0.20 ± --- | 1 PLACE ± --- ± --- | APPROVED BY SHLENI | DATE 2010/12/15 | | | |
| 0 PLACE ± --- ± --- | | ANGULAR ± 1 ° | | SEE TABLE | | | | | | |
| DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS | | | | SIZE A3 | | THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION | | | | |

9 8 7 6 5 4 3 2 1

10 9 8 7 6 5 4 3 2 1

009MODULE CARD
 DDR3 DUAL INLINE MEMORY MODULE FAMILY 1.00 CONTACT CENTERS
 (JEDEC MO-269, ISSUE A, 12/05)



NOTES:

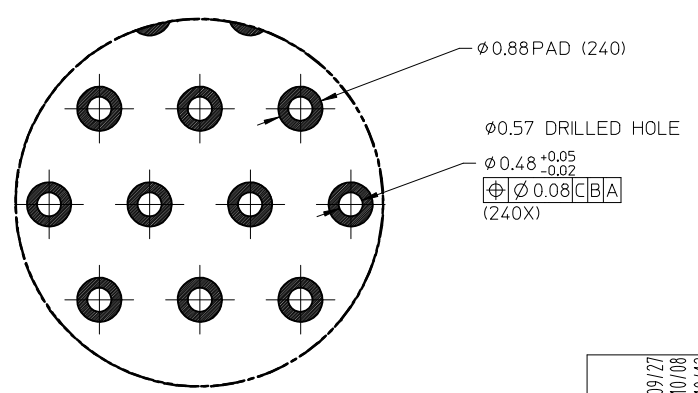
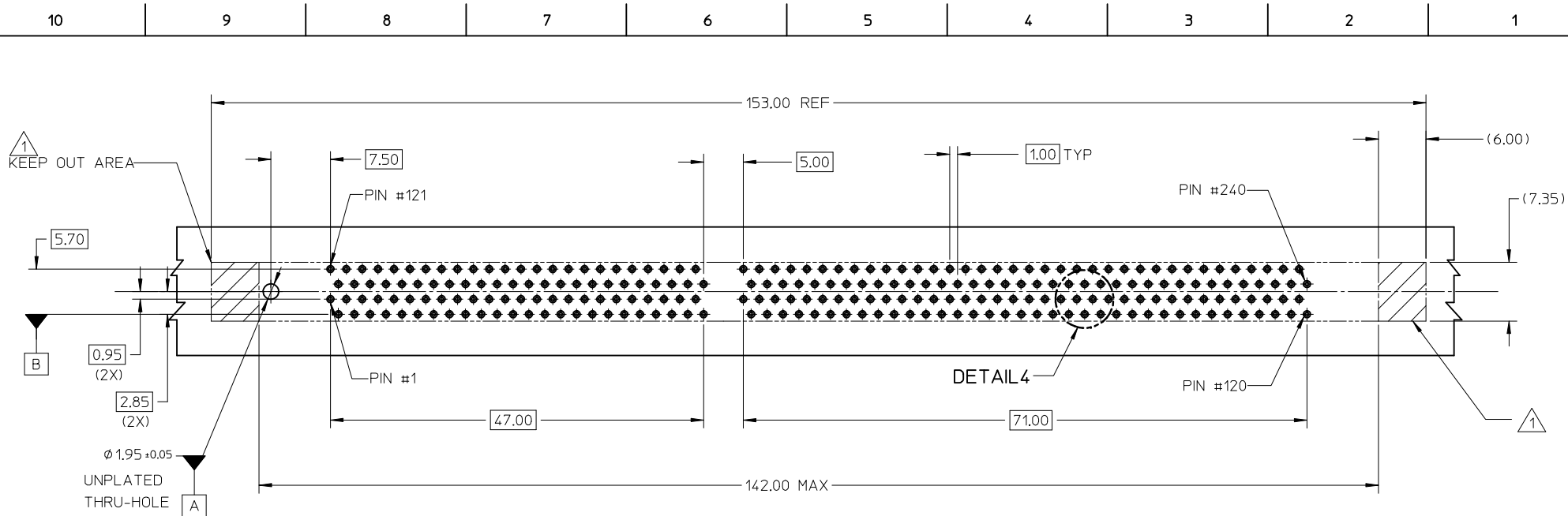
1. RECOMMENDED PLATING FOR CONTACT PADS:
 PREFERRED: 0.76 MICROMETERS GOLD PLATING MIN
 OVER 2.00 MICROMETERS NICKEL
 ALTERNATIVE: 0.05-0.75 MICROMETERS GOLD PLATING
 OVER 2.00 MICROMETERS NICKEL MUST
 USE AN ELECTRONIC CONTACT GRADE
 CORROSIVE BARRIER LUBRICANT

2. CHAMFER IS OPTIONAL AND IS NOT TO HIT THE GOLD PADS

3. LEADING EDGE OF GOLD PADS SPECIFIED BY KEEPOUT ZONE
 SHALL BE FREE OF BURRS AND EXTERNAL TIE BARS

| | | | | | | | | | | |
|--|---|---------------------------------------|--|----------------------------|--|--------------------|--|------------------------|--|--|
| OBS. 78315-0201 EC NO: S2013-0172 DRW: CCTEH 2012/09/27 CHKD: CGTAN 2012/10/08 APPR: SHLENI 2012/10/12 | QUALITY SYMBOLS FA=0 FG=0 FP=0 | GENERAL TOLERANCES (UNLESS SPECIFIED) | | DIMENSION STYLE MM ONLY | | SCALE NTS | DESIGN UNITS METRIC | THIRD ANGLE PROJECTION | | |
| | | | mm | INCH | DRAWN BY CMTEO | DATE 2008/07/17 | TITLE DDR3 DIMM (LSP, VLP) 1.00MM PITCH, 240 CKTS VERTICAL P/F, LOWLLCR | | | |
| | | 4 PLACES | ± --- | ± --- | CHECKED BY CCTEH | DATE 2008/07/30 | molex | | | |
| | | 3 PLACES | ± --- | ± --- | APPROVED BY SHLENI | DATE 2010/12/15 | | | | |
| 2 PLACES | ± 0.20 | ± --- | MATERIAL NO. | | DOCUMENT NO. | | SHEET NO. | | | |
| 1 PLACE | ± --- | ± --- | SEE TABLE | | SD-78315-001 | | 3 OF 6 | | | |
| 0 PLACE | ± --- | ± --- | DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS | | THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION | | | | | |

9 8 7 6 5 4 3 2 1

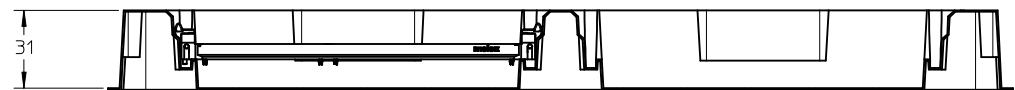
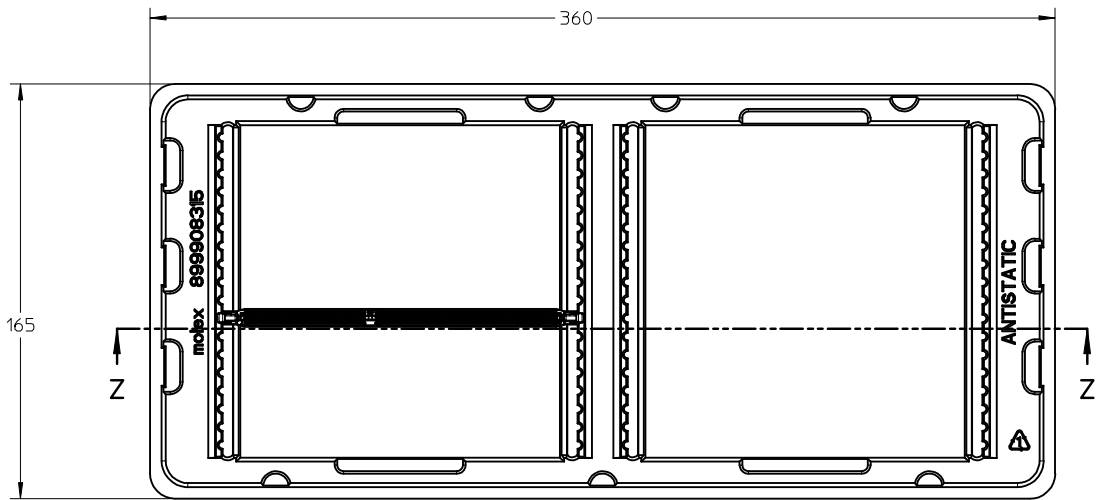


NOTES:
 1. KEEP OUT AREA IS THE AREA WHERE THE CONNECTOR (INCLUDING LATCH) IS MOUNTED ON THE PCB

| | | | | | | | | | | | |
|---|-------------------|-----------------|---------------------------------------|--|----------------------------|--------------------|--|---|------------------------|--------|--|
| OBS. 78315-0201 EC NO: S2013-0172 DRWN: CCTEH 2012/09/27 CHKD: CGTAN 2012/10/08 APPR: SHLENI 2012/10/12 | DESCRIPTION A2 | QUALITY SYMBOLS | GENERAL TOLERANCES (UNLESS SPECIFIED) | | DIMENSION STYLE MM ONLY | | SCALE NTS | DESIGN UNITS METRIC | THIRD ANGLE PROJECTION | | |
| | | $F_A=0$ | mm | INCH | DRAWN BY CMTEO | DATE 2008/07/17 | TITLE DDR3 DIMM (LSP, VLP) 1.00MM PITCH, 240 CKTS VERTICAL P/F, LOWLLCR | | | | |
| | | $F_G=0$ | 4 PLACES ± --- | ± --- | CHECKED BY CCTEH | DATE 2008/07/30 | molex SD-78315-001 | | | | |
| | | $F_P=0$ | 3 PLACES ± --- | ± --- | APPROVED BY SHLENI | DATE 2010/12/15 | | | | | |
| | | 2 PLACES ± 0.20 | ± --- | MATERIAL NO. | | SEE TABLE | | SD-78315-001 | | 4 OF 6 | |
| | | 1 PLACE ± --- | ± --- | DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS | | SIZE A3 | | THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION | | | |
| | | 0 PLACE ± --- | ± --- | | | | | | | | |

10 9 8 7 6 5 4 3 2 1

VIEW FOR PACKAGING TRAY



SECTION Z-Z


NOTE:
1. NO. OF CAVITY - 18 X 2 =36

| OBS. 78315-0201 EC NO: S2013-0172 DRWN: CCTEH 2012/09/27 CHKD: CGTAN 2012/10/08 APPR: SHLENI 2012/10/12 REV A2 | QUALITY SYMBOLS | GENERAL TOLERANCES (UNLESS SPECIFIED) | DIMENSION STYLE | SCALE | DESIGN UNITS | THIRD ANGLE PROJECTION | | | | | | | | | | | | | | | | | | |
|---|---|--|-----------------|-------|--------------|------------------------|---|-------|------------|--------|------------|-----------|--------------|-------|---------|-------|-------|---------|-------|-------|---------|-----|--------|--|
| | $\nabla_{\sqrt{R}}=0$ $\nabla_{\sqrt{G}}=0$ $\nabla_{\sqrt{F}}=0$ | <table border="1"> <thead> <tr> <th></th> <th>mm</th> <th>INCH</th> </tr> </thead> <tbody> <tr> <td>4 PLACES</td> <td>± ---</td> <td>± ---</td> </tr> <tr> <td>3 PLACES</td> <td>± ---</td> <td>± ---</td> </tr> <tr> <td>2 PLACES</td> <td>± 0.20</td> <td>± ---</td> </tr> <tr> <td>1 PLACE</td> <td>± ---</td> <td>± ---</td> </tr> <tr> <td>0 PLACE</td> <td>± ---</td> <td>± ---</td> </tr> </tbody> </table> | | mm | INCH | 4 PLACES | ± --- | ± --- | 3 PLACES | ± --- | ± --- | 2 PLACES | ± 0.20 | ± --- | 1 PLACE | ± --- | ± --- | 0 PLACE | ± --- | ± --- | MM ONLY | NTS | METRIC | |
| | | mm | INCH | | | | | | | | | | | | | | | | | | | | | |
| | 4 PLACES | ± --- | ± --- | | | | | | | | | | | | | | | | | | | | | |
| 3 PLACES | ± --- | ± --- | | | | | | | | | | | | | | | | | | | | | | |
| 2 PLACES | ± 0.20 | ± --- | | | | | | | | | | | | | | | | | | | | | | |
| 1 PLACE | ± --- | ± --- | | | | | | | | | | | | | | | | | | | | | | |
| 0 PLACE | ± --- | ± --- | | | | | | | | | | | | | | | | | | | | | | |
| ANGULAR ± 1 ° DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS | <table border="1"> <thead> <tr> <th>DRAWN BY</th> <th>DATE</th> <th>TITLE</th> </tr> </thead> <tbody> <tr> <td>CMTEO</td> <td>2008/07/17</td> <td rowspan="3">DDR3 DIMM (LSP, VLP) 1.00MM PITCH, 240 CKTS VERTICAL P/F, LOWLLCR</td> </tr> <tr> <td>CCTEH</td> <td>2008/07/30</td> </tr> <tr> <td>SHLENI</td> <td>2010/12/15</td> </tr> </tbody> </table> | DRAWN BY | DATE | TITLE | CMTEO | 2008/07/17 | DDR3 DIMM (LSP, VLP) 1.00MM PITCH, 240 CKTS VERTICAL P/F, LOWLLCR | CCTEH | 2008/07/30 | SHLENI | 2010/12/15 | SEE TABLE | DOCUMENT NO. | | | | | | | | | | | |
| DRAWN BY | DATE | TITLE | | | | | | | | | | | | | | | | | | | | | | |
| CMTEO | 2008/07/17 | DDR3 DIMM (LSP, VLP) 1.00MM PITCH, 240 CKTS VERTICAL P/F, LOWLLCR | | | | | | | | | | | | | | | | | | | | | | |
| CCTEH | 2008/07/30 | | | | | | | | | | | | | | | | | | | | | | | |
| SHLENI | 2010/12/15 | | | | | | | | | | | | | | | | | | | | | | | |
| | | THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION | | | | | | | | | | | | | | | | | | | | | | |

9 8 7 6 5 4 3 2 1

10 | 9 | 8 | 7 | 6 | 5 | 4 | 3 | 2 | 1

| PART NO. | KEY POS. | DIM 'P' | RECOMMENDED PCB THICKNESS | PLATING OPTION | | LATCH COLOUR | HOUSING COLOUR |
|------------|---------------|---------|---------------------------|--|--|--------------|----------------|
| | | | | CONTACT AREA | TAIL AREA | | |
| 78315-0001 | CENTER (1.5V) | 1.85 | 2.40 | 0.76 MICROMETER/ 30 MICROINCH MIN. GOLD OVER 1.27 MICROMETER/ 50 MICROINCH MIN. NICKEL UNDERPLATE | 0.38 TO 1.52 MICROMETER/15 TO 60 MICROINCH MIN TIN (MATT) OVER 1.27 MICROMETER/ 50 MICROINCH MIN. NICKEL UNDERPLATE | BLACK | BLACK |
| 78315-0051 | | | | | | BLUE | BLUE |
| 78315-0011 | | 2.85 | 2.60 | | | BLACK | BLACK |

| | | | | | | | | |
|---|--|--|--------------|-----------------|---|---|------------------------|---|
| OBS. 78315-0201 EC NO: S2013-0172 DRWN: CTEH 2012/09/27 CHKD: CGTAN 2012/10/08 APPR: SHLENI 2012/10/12 | QUALITY SYMBOLS $F_A=0$ $F_G=0$ $F_P=0$ | GENERAL TOLERANCES (UNLESS SPECIFIED) | | DIMENSION STYLE | SCALE | DESIGN UNITS | THIRD ANGLE PROJECTION | |
| | | | | MM ONLY | NTS | METRIC | | |
| | | | | mm | INCH | DRAWN BY | DATE | TITLE |
| | | | | 4 PLACES | ± --- ± --- | CMTEO | 2008/07/17 | DDR3 DIMM (LSP, VLP) 1.00MM PITCH, 240 CKTS VERTICAL P/F, LOWLLCR |
| | | | | 3 PLACES | ± --- ± --- | CHECKED BY | DATE | |
| | | 2 PLACES | ± 0.20 ± --- | CTEH | 2008/07/30 |  | | |
| | | 1 PLACE | ± --- ± --- | APPROVED BY | DATE | | | |
| | | 0 PLACE | ± --- ± --- | SHLENI | 2010/12/15 | | | |
| | | ANGULAR ± 1 ° | | MATERIAL NO. | DOCUMENT NO. | | SHEET NO. | |
| | | DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS | | SEE TABLE | SD-78315-001 | | 6 OF 6 | |
| | | | | SIZE | THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION | | | |
| A2 | | | | A3 | | | | |

9 | 8 | 7 | 6 | 5 | 4 | 3 | 2 | 1